

AMENDMENT TO THE SPECIFICATION

PLEASE replace the paragraph at page 10, lines 10 through 25, with the following:

The organic solvents used to dissolve the trimethylbismuth include tetrahydrofuran, methyl ethyl ketone, isopropanol, methanol, xylene, n-butyl acetate, octane, hexamethyldisilane (HMDS), 2-methoxyethanol, hexane, toluene, diethylethane, 1,4-dioxane and ethanol. Such solvents can be used alone or as a mixture thereof. An initiator, such as methyl ethyl ketone (MEK), may be added just before misting. A more complete list of solvents and initiators as well as specific examples of metal compounds are included in U.S. Patent Application No. ~~08/477,111~~ filed ~~June 7, 1995~~ 6,056,994 issued May 2, 2000 to Paz de Araujo et al. and U.S. Patent No. 5,614,252, issued March 25, 1997 to McMillan et al., which are hereby incorporated by reference to the same extent as if fully set forth herein. For the organic solvent, tetrahydrofuran can be used alone or in a mixture with at least one of the above-exemplified solvents in order to obtain a uniform solution since the trimethylbismuth dissolves well in the tetrahydrofuran, and thus, composition homogeneity of the Bi-layered superlattice material thin film is improved. It is preferable that the organic solvent contains tetrahydrofuran. Trimethylbismuth dissolves well into tetrahydrofuran and thereby allows for a homogeneous Bi-layered superlattice material composition to be provided.